

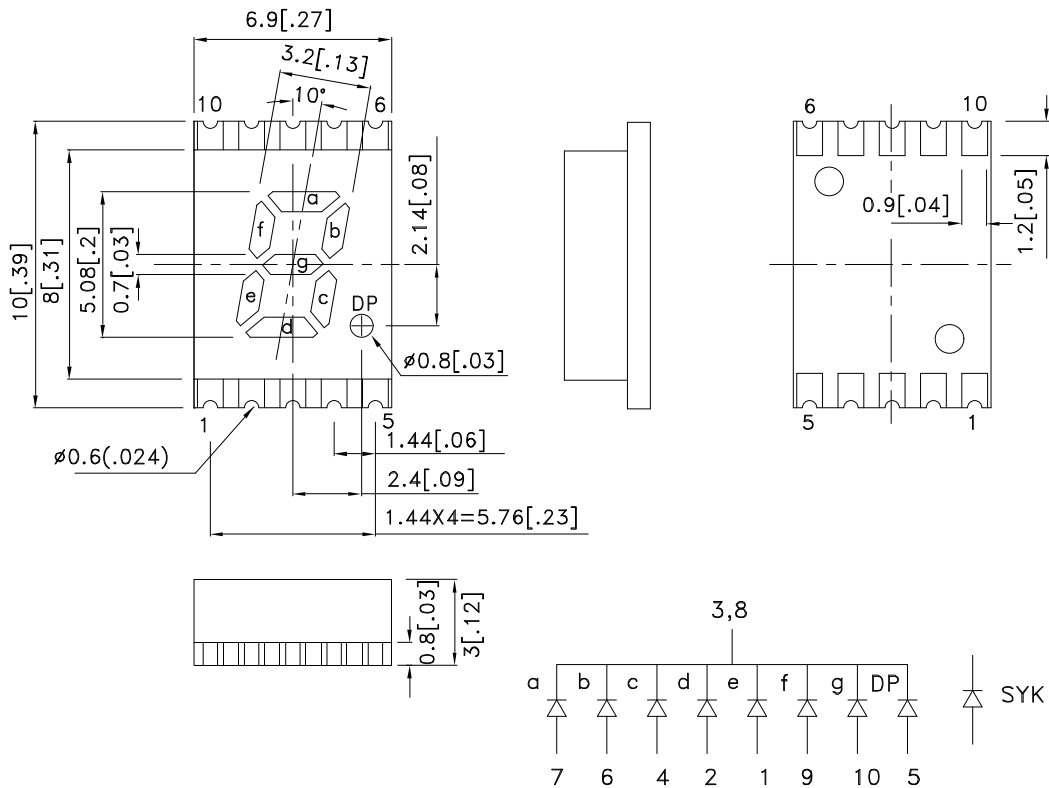
### Features

- 0.2INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE
- MECHANICALLY RUGGED.
- GRAY FACE,WHITE SEGMENT.
- PACKAGE : 650PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

### Description

The Super Bright Yellow device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

### Package Dimensions& Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.



## Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
KCSC02-107	Super Bright Yellow (InGaAlP)	WHITE DIFFUSED	8000	34000	Common Cathode, Rt. Hand Decimal.

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Super Bright Yellow	590		nm	I <sub>F</sub> =20mA
$\lambda_D$ [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I <sub>F</sub> =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Yellow	20		nm	I <sub>F</sub> =20mA
C	Capacitance	Super Bright Yellow	20		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Super Bright Yellow	2.0	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Super Bright Yellow		10	uA	V <sub>R</sub> =5V

Notes:

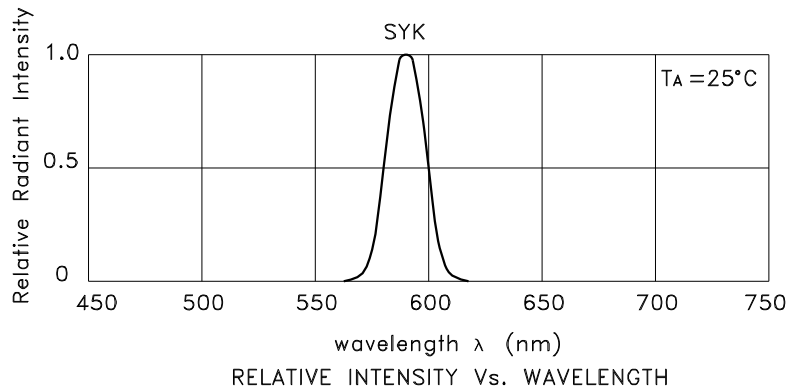
1. Wavelength: +/-1nm.  
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

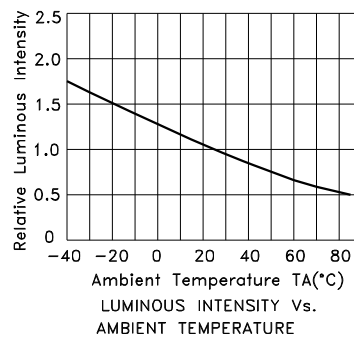
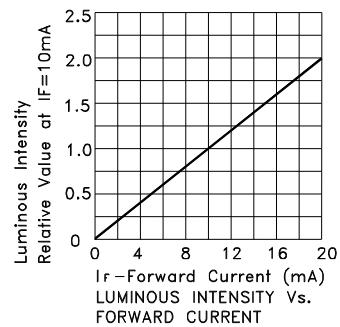
Parameter	Super Bright Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	175	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



**Super Bright Yellow KCSC02-107**



## KCSC02-107

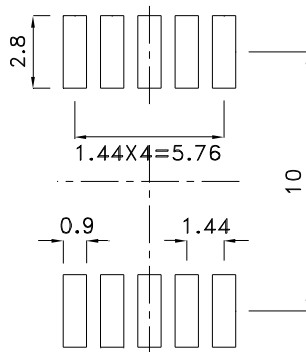
Reflow Soldering Profile For Lead-free SMT Process.



**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.15)



### Tape Specifications (Units : mm)

